## Fast IGBT in NPT-technology

- 75% lower E_{off} compared to previous generation combined with low conduction losses

- Short circuit withstand time – 10 μs

- Designed for:
  - Motor controls
  - Inverter

- NPT-Technology for 600V applications offers:
  - very tight parameter distribution
  - high ruggedness, temperature stable behaviour
  - parallel switching capability

- Qualified according to JEDEC[1] for target applications
- Pb-free lead plating; RoHS compliant
- Complete product spectrum and PSpice Models : http://www.infineon.com/igbt/

PG-TO-247-3
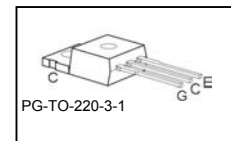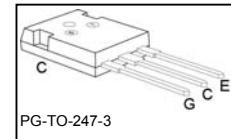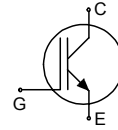
PG-TO-220-3-1

Type	V_{CE}	I_C	$V_{CE(sat)}$	T_j	Marking	Package
SGP10N60A	600V	10A	2.3V	150°C	G10N60A	PG-TO-220-3-1
SGW10N60A	600V	10A	2.3V	150°C	G10N60A	PG-TO-247-3

Maximum Ratings

Parameter	Symbol	Value	Unit
Collector-emitter voltage	V_{CE}	600	V
DC collector current	I_C		A
T_C = 25°C		20	
T_C = 100°C		10.6	
Pulsed collector current, t_p limited by T_{jmax}	I_{Cpuls}	40	
Turn off safe operating area $V_{CE} \leq 600V$, $T_j \leq 150°C$	-	40	
Gate-emitter voltage	V_{GE}	±20	V
Avalanche energy, single pulse I_C = 10 A, V_{CC} = 50 V, R_{GE} = 25 Ω, start at T_j = 25°C	E_{AS}	70	mJ
Short circuit withstand time[2] V_{GE} = 15V, $V_{CC} \leq 600V$, $T_j \leq 150°C$	t_{SC}	10	μs
Power dissipation T_C = 25°C	P_{tot}	92	W
Operating junction and storage temperature	T_j , T_{stg}	-55...+150	°C
Soldering temperature, wavesoldering, 1.6mm (0.063 in.) from case for 10s	T_s	260	

[1] J-STD-020 and JESD-022
[2] Allowed number of short circuits: <1000; time between short circuits: >1s.

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Thermal Resistance

Parameter	Symbol	Conditions	Max. Value	Unit
Characteristic				
IGBT thermal resistance, junction – case	R_{thJC}		1.35	K/W
Thermal resistance, junction – ambient	R_{thJA}	PG-TO-220-3-1	62	
		PG-TO-247-3-21	40	

Electrical Characteristic, at T_j = 25 °C, unless otherwise specified

Parameter	Symbol	Conditions	Value			Unit
			min.	Typ.	max.	
Static Characteristic						
Collector-emitter breakdown voltage	$V_{(BR)CES}$	V_{GE}=0V, I_C=500µA	600	-	-	V
Collector-emitter saturation voltage	$V_{CE(sat)}$	V_{GE} = 15V, I_C=10A				
		T_j=25°C	1.7	2	2.4	
		T_j=150°C	-	2.3	2.8	
Gate-emitter threshold voltage	$V_{GE(th)}$	I_C=300µA, V_{CE}=V_{GE}	3	4	5	
Zero gate voltage collector current	I_{CES}	V_{CE}=600V, V_{GE}=0V				µA
		T_j=25°C	-	-	40	
		T_j=150°C	-	-	1500	
Gate-emitter leakage current	I_{GES}	V_{CE}=0V, V_{GE}=20V	-	-	100	nA
Transconductance	g_{fs}	V_{CE}=20V, I_C=10A	-	6.7	-	S
Dynamic Characteristic						
Input capacitance	C_{iss}	V_{CE}=25V,	-	550	660	pF
Output capacitance	C_{oss}	V_{GE}=0V,	-	62	75	
Reverse transfer capacitance	C_{rss}	f=1MHz	-	42	51	
Gate charge	Q_{Gate}	V_{CC}=480V, I_C=10A V_{GE}=15V	-	52	68	nC
Internal emitter inductance measured 5mm (0.197 in.) from case	L_E	PG-TO-220-3-1	-	7	-	nH
		PG-TO-247-3-21	-	13	-	
Short circuit collector current[2]	$I_{C(SC)}$	V_{GE}=15V, t_{SC}≤10µs V_{CC} ≤ 600V, T_j ≤ 150°C	-	100	-	A

[2] Allowed number of short circuits: <1000; time between short circuits: >1s.

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Switching Characteristic, Inductive Load, at T_j=25 °C

Parameter	Symbol	Conditions	Value			Unit
			min.	typ.	max.	
IGBT Characteristic						
Turn-on delay time	$t_{d(on)}$	T_j=25°C, V_{CC}=400V, I_C=10A, V_{GE}=0/15V, R_G=25Ω, $L_\sigma{}^{1)}$ =180nH, $C_\sigma{}^{1)}$ =55pF Energy losses include "tail" and diode reverse recovery.	-	28	34	ns
Rise time	t_r		-	12	15	
Turn-off delay time	$t_{d(off)}$		-	178	214	
Fall time	t_f		-	24	29	
Turn-on energy	E_{on}		-	0.15	0.173	mJ
Turn-off energy	E_{off}		-	0.17	0.221	
Total switching energy	E_{ts}		-	0.320	0.394	

Switching Characteristic, Inductive Load, at T_j=150 °C

| Parameter	Symbol	Conditions	Value			Unit
			min.	typ.	max.	
IGBT Characteristic						
Turn-on delay time	$t_{d(on)}$	T_j=150°C V_{CC}=400V, I_C=10A, V_{GE}=0/15V, R_G=25Ω $L_\sigma{}^{1)}$ =180nH, $C_\sigma{}^{1)}$ =55pF Energy losses include "tail" and diode reverse recovery.	-	28	34	ns
Rise time	t_r		-	12	15	
Turn-off delay time	$t_{d(off)}$		-	198	238	
Fall time	t_f		-	26	32	
Turn-on energy	E_{on}		-	0.260	0.299	mJ
Turn-off energy	E_{off}		-	0.280	0.364	
Total switching energy	E_{ts}		-	0.540	0.663	

[1] Leakage inductance L_σ and Stray capacity C_σ due to dynamic test circuit in Figure E.

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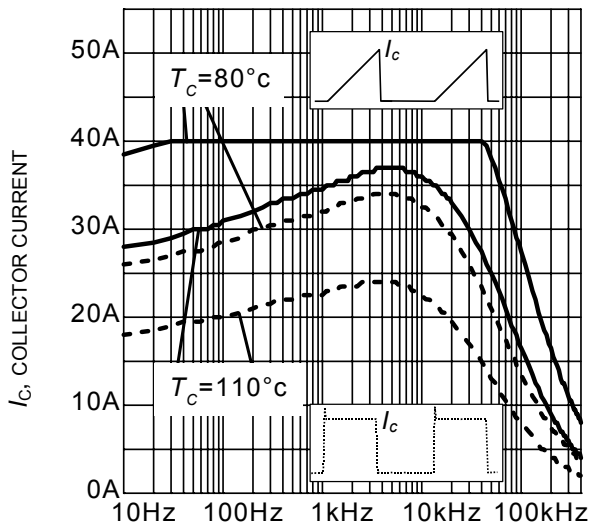
f, SWITCHING FREQUENCY

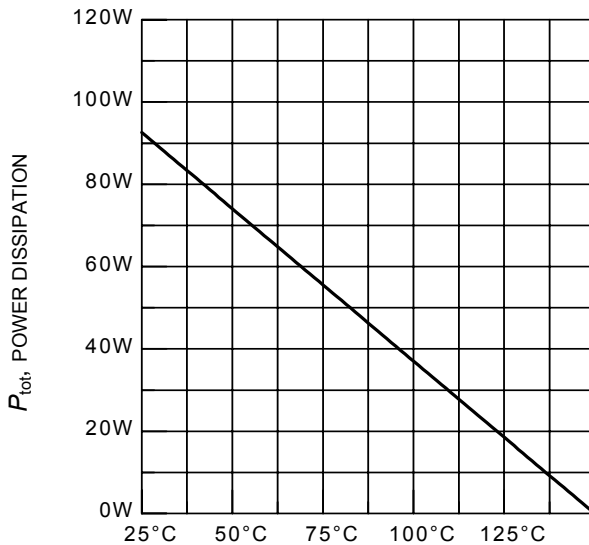**Figure 1. Collector current as a function of switching frequency**
($T_j \le 150°C$, $D = 0.5$, $V_{CE} = 400V$,
$V_{GE} = 0/+15V$, $R_G = 25\Omega$)
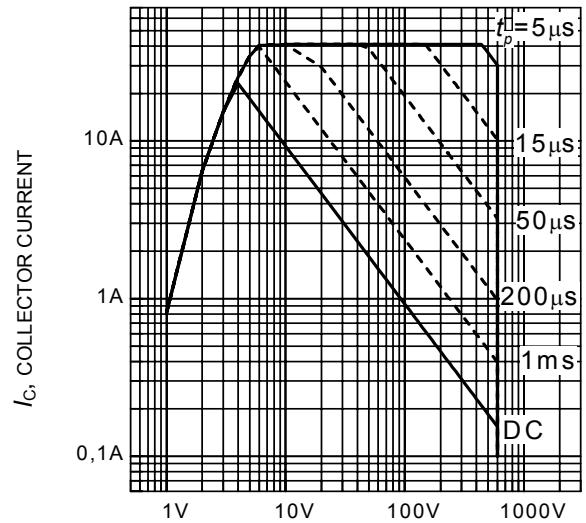
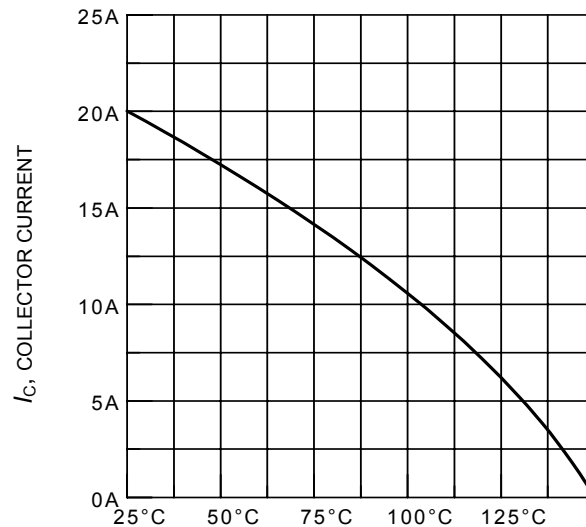V_{CE}, COLLECTOR-EMITTER VOLTAGE

Figure 2. Safe operating area
($D = 0$, $T_C = 25°C$, $T_j \le 150°C$)

T_C, CASE TEMPERATURE

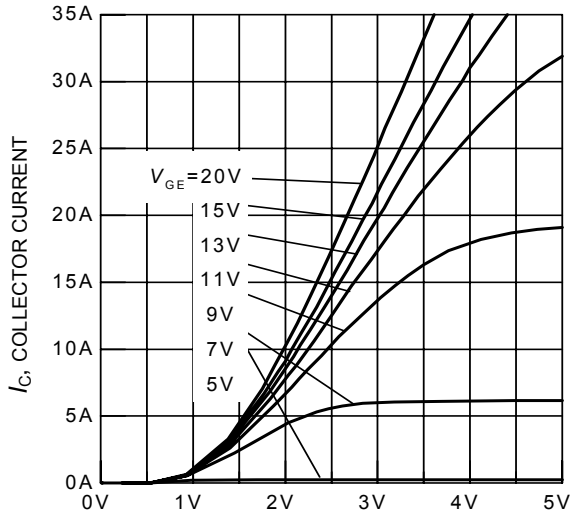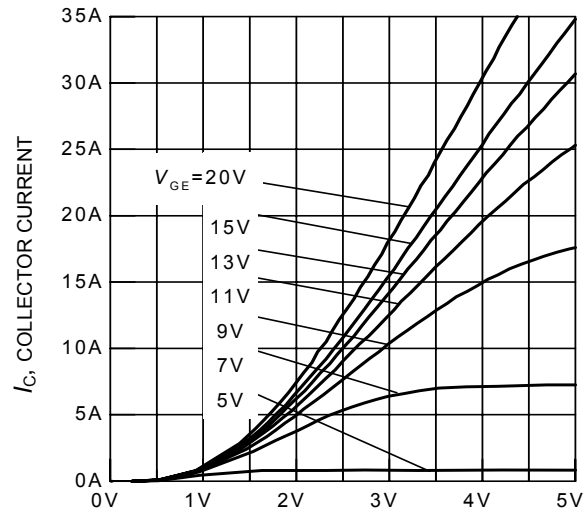**Figure 3. Power dissipation as a function of case temperature**
($T_j \le 150°C$)

T_C, CASE TEMPERATURE

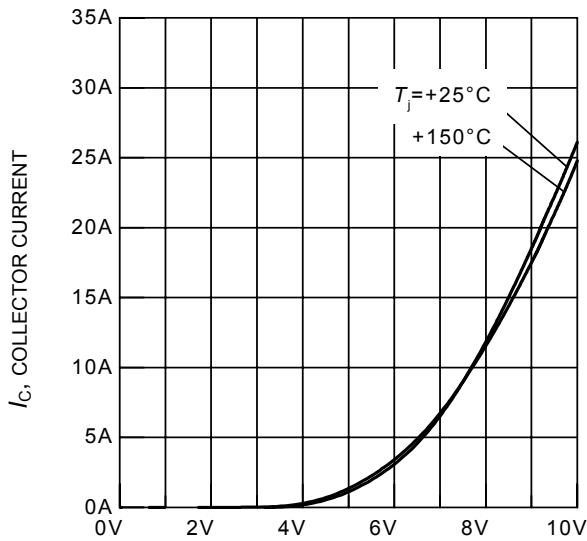**Figure 4. Collector current as a function of case temperature**
($V_{GE} \le 15V$, $T_j \le 150°C$)

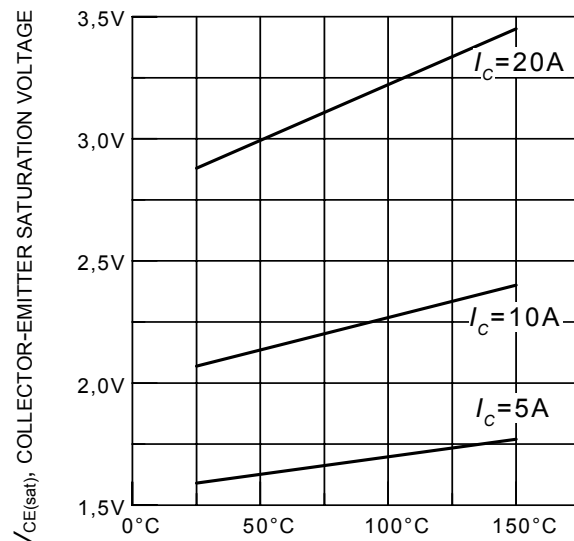**Figure 5. Typical output characteristics**
(T_j = 25°C)

Figure 6. Typical output characteristics
(T_j = 150°C)

Figure 7. Typical transfer characteristics
(V_{CE} = 10V)
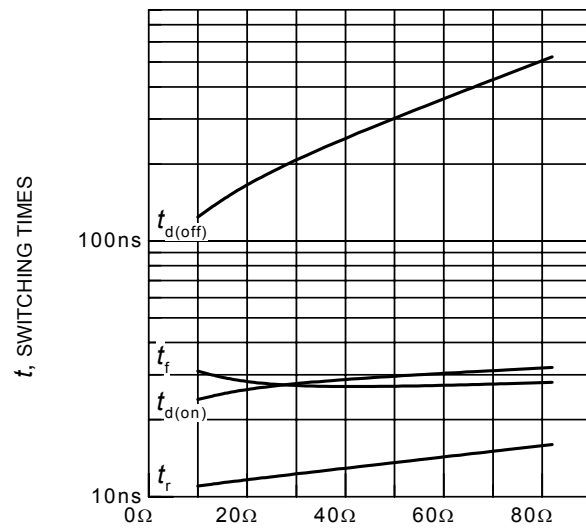

Figure 8. Typical collector-emitter saturation voltage as a function of junction temperature
(V_{GE} = 15V)

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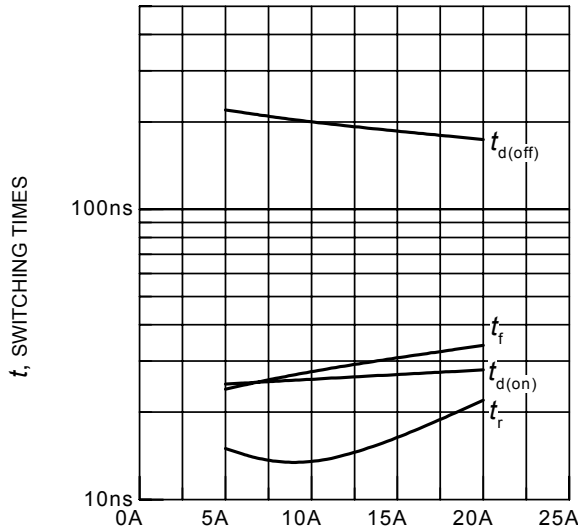
I_C, COLLECTOR CURRENT

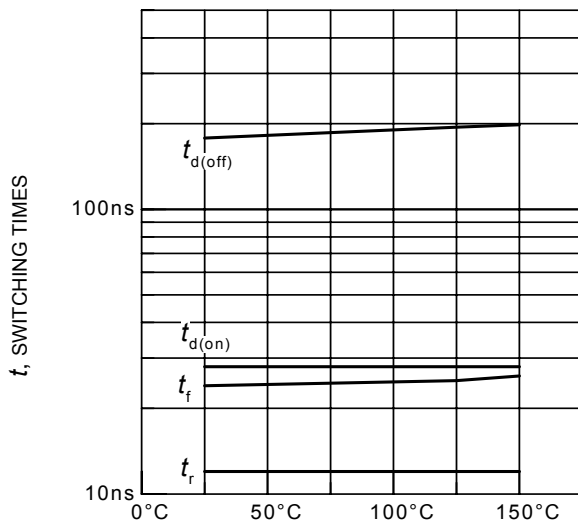**Figure 9. Typical switching times as a function of collector current**
(inductive load, T_j = 150°C, V_{CE} = 400V, V_{GE} = 0/+15V, R_G = 25Ω, Dynamic test circuit in Figure E)

R_G, GATE RESISTOR

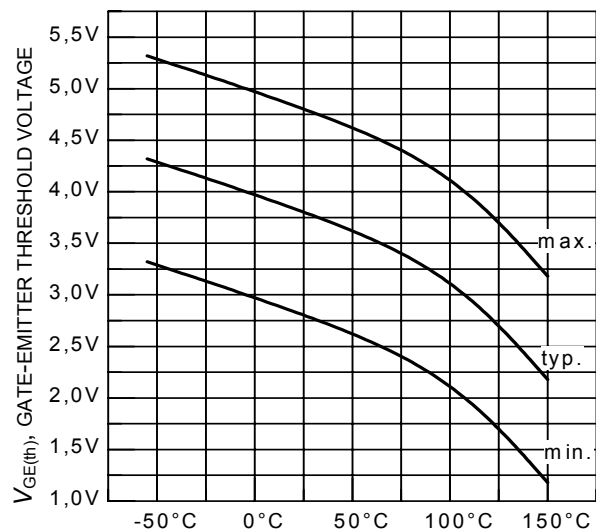**Figure 10. Typical switching times as a function of gate resistor**
(inductive load, T_j = 150°C, V_{CE} = 400V, V_{GE} = 0/+15V, I_C = 10A, Dynamic test circuit in Figure E)

T_j, JUNCTION TEMPERATURE

Figure 11. Typical switching times as a function of junction temperature
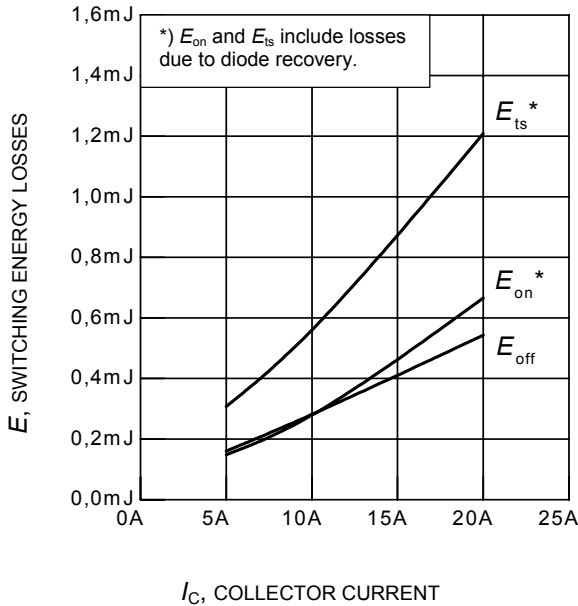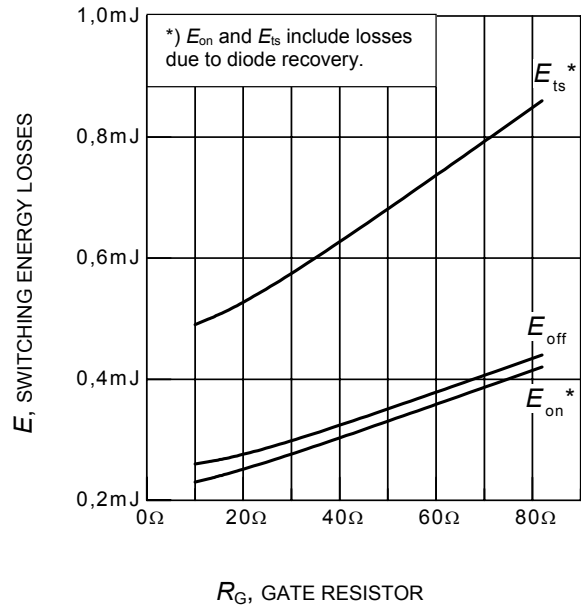(inductive load, V_{CE} = 400V, V_{GE} = 0/+15V, I_C = 10A, R_G = 25Ω, Dynamic test circuit in Figure E)

T_j, JUNCTION TEMPERATURE

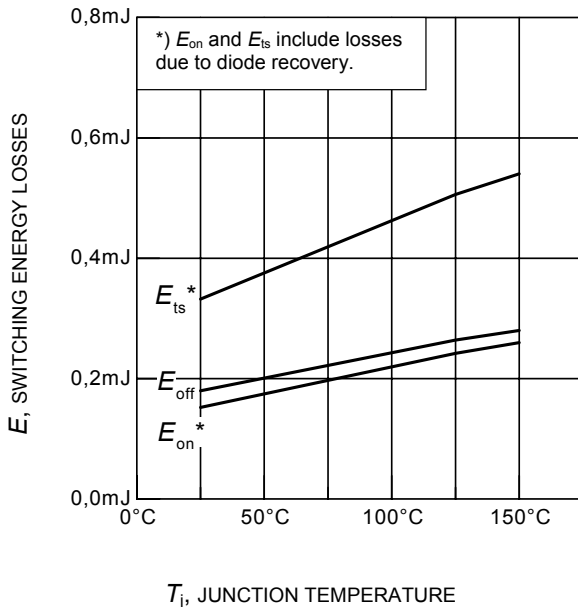**Figure 12. Gate-emitter threshold voltage as a function of junction temperature**
(I_C = 0.3mA)

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Figure 13. Typical switching energy losses as a function of collector current
(inductive load, T_j = 150°C, V_{CE} = 400V, V_{GE} = 0/+15V, R_G = 25Ω, Dynamic test circuit in Figure E)

Figure 14. Typical switching energy losses as a function of gate resistor
(inductive load, T_j = 150°C, V_{CE} = 400V, V_{GE} = 0/+15V, I_C = 10A, Dynamic test circuit in Figure E)

Figure 15. Typical switching energy losses as a function of junction temperature
(inductive load, V_{CE} = 400V, V_{GE} = 0/+15V, I_C = 10A, R_G = 25Ω, Dynamic test circuit in Figure E)
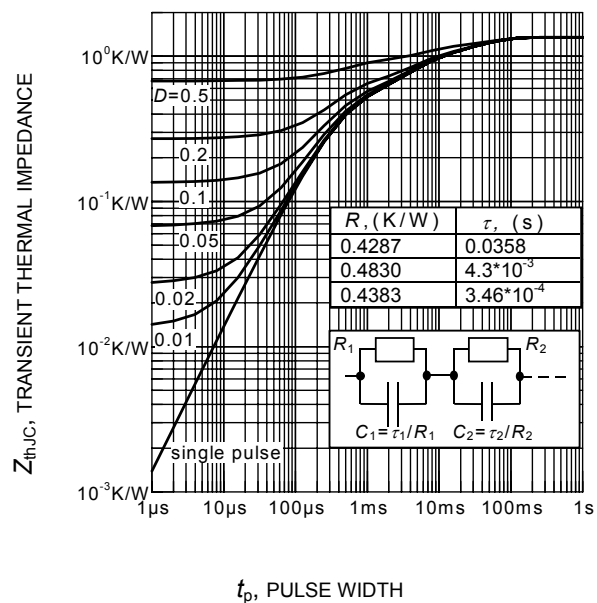
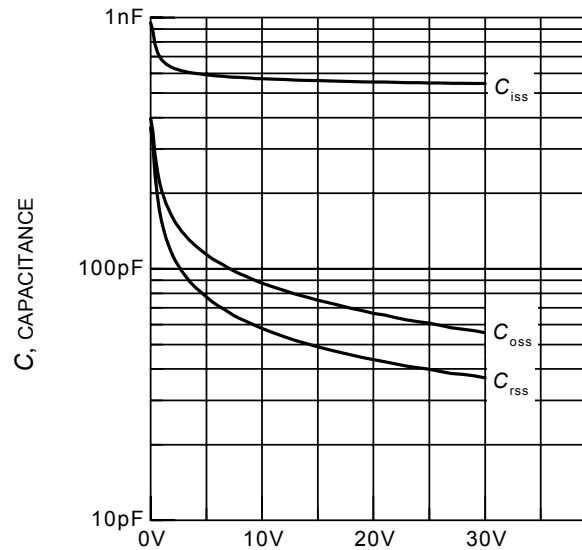**Figure 16. IGBT transient thermal impedance as a function of pulse width**
($D = t_p / T$)

R, (K/W)	τ, (s)
0.4287	0.0358
0.4830	$4.3*10^{-3}$
0.4383	$3.46*10^{-4}$

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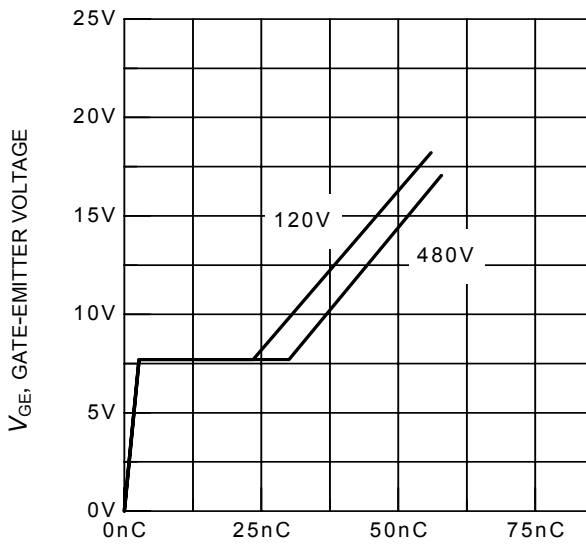
Q_{GE}, GATE CHARGE
Figure 17. Typical gate charge
(I_C = 10A)

V_{CE}, COLLECTOR-EMITTER VOLTAGE
Figure 18. Typical capacitance as a function of collector-emitter voltage
(V_{GE} = 0V, f = 1MHz)
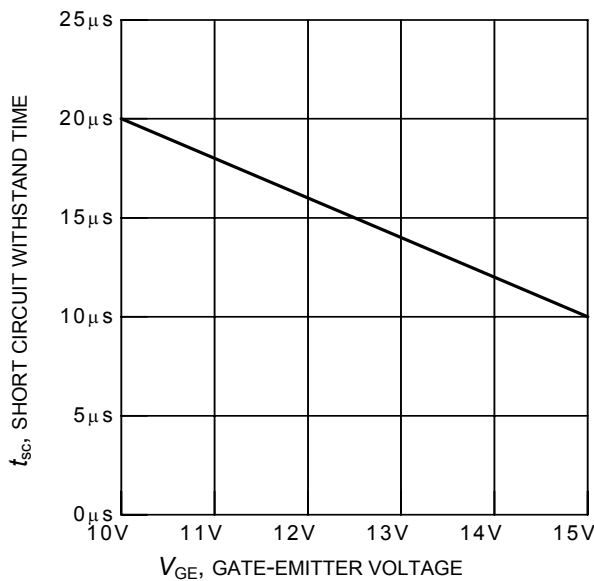
V_{GE}, GATE-EMITTER VOLTAGE
Figure 19. Short circuit withstand time as a function of gate-emitter voltage
(V_{CE} = 600V, start at T_j = 25°C)
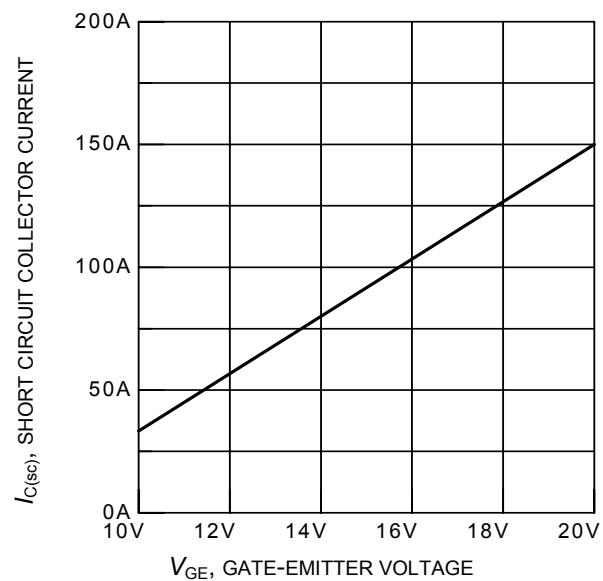
V_{GE}, GATE-EMITTER VOLTAGE
Figure 20. Typical short circuit collector current as a function of gate-emitter voltage
($V_{CE} \leq$ 600V, T_j = 150°C)

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PG-TO220-3-1

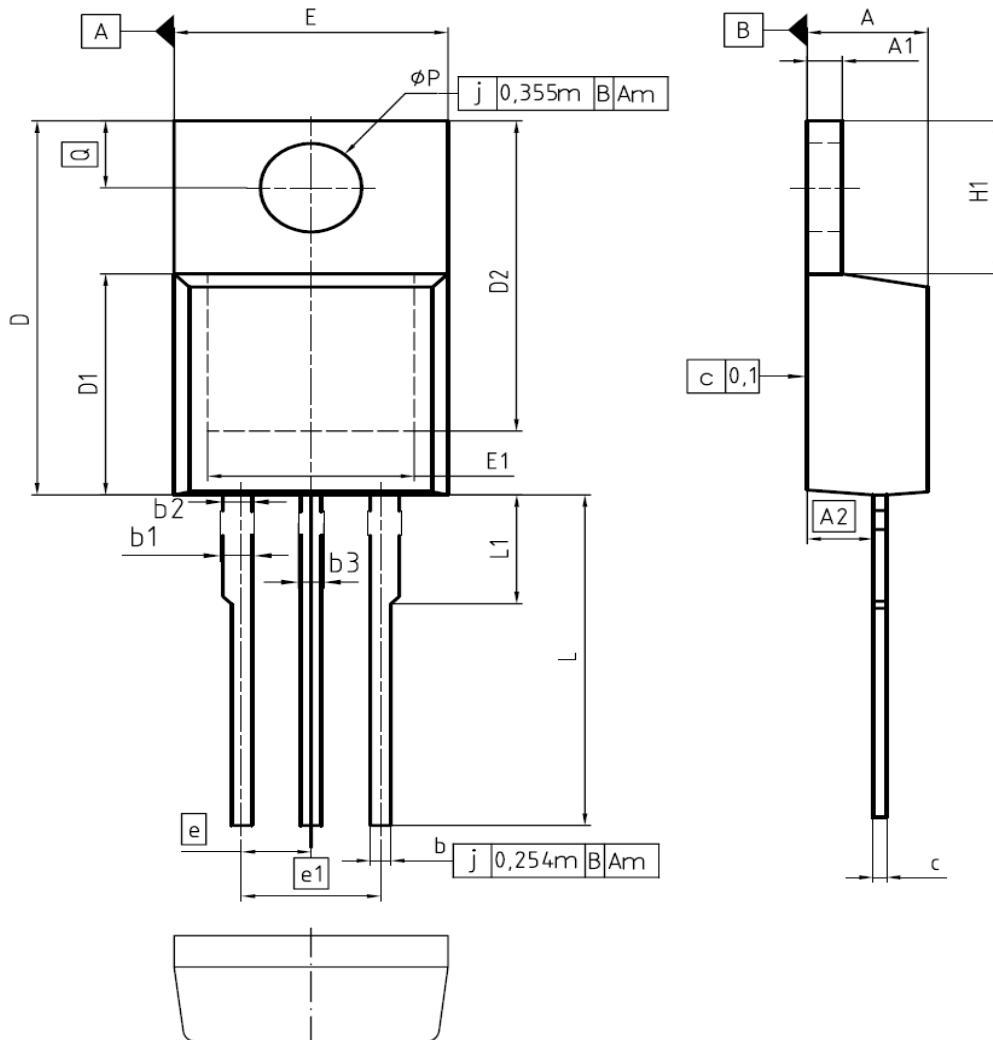| DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4.30	4.57	0.169	0.180
A1	1.17	1.40	0.046	0.055
A2	2.15	2.72	0.085	0.107
b	0.65	0.86	0.026	0.034
b1	0.95	1.40	0.037	0.055
b2	0.95	1.15	0.037	0.045
b3	0.65	1.15	0.026	0.045
c	0.33	0.60	0.013	0.024
D	14.81	15.95	0.583	0.628
D1	8.51	9.45	0.335	0.372
D2	12.19	13.10	0.480	0.516
E	9.70	10.36	0.382	0.408
E1	6.50	8.60	0.256	0.339
e	2.54		0.100	
e1	5.08		0.200	
N	3		3	
H1	5.90	6.90	0.232	0.272
L	13.00	14.00	0.512	0.551
L1	-	4.80	-	0.189
øP	3.60	3.89	0.142	0.153
Q	2.60	3.00	0.102	0.118

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SCALE

EUROPEAN PROJECTION

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05

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TO247-3
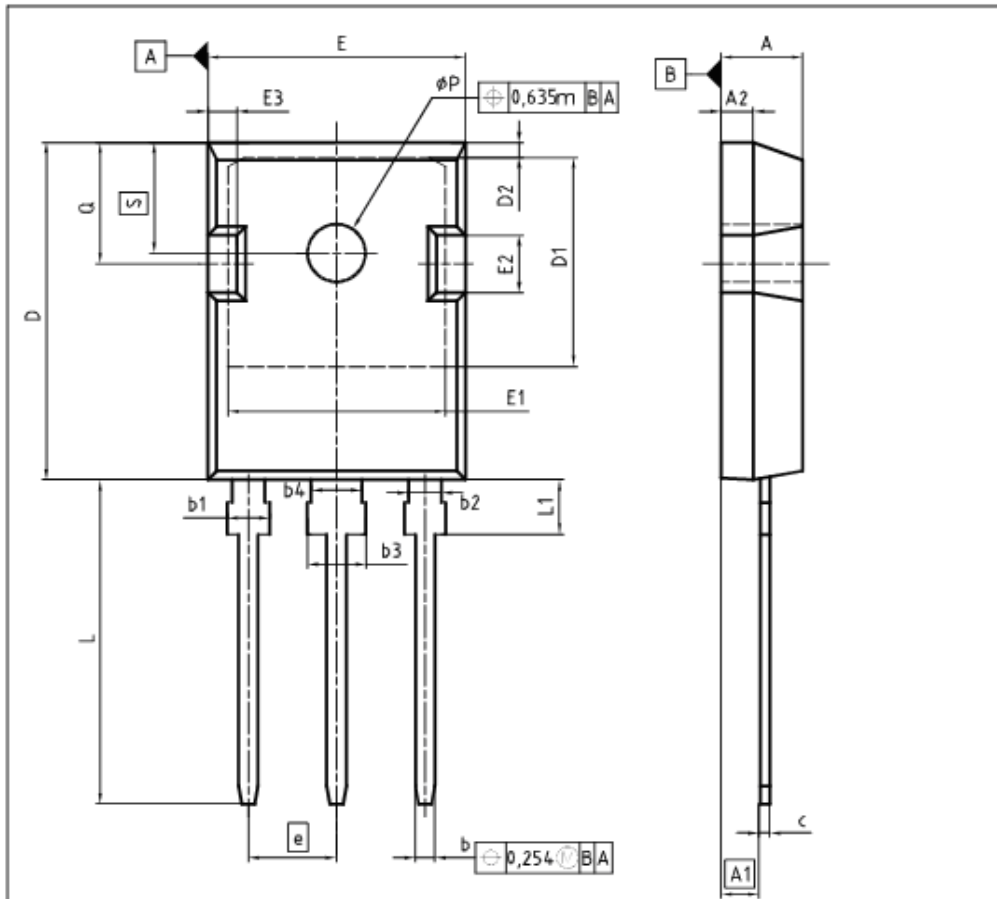
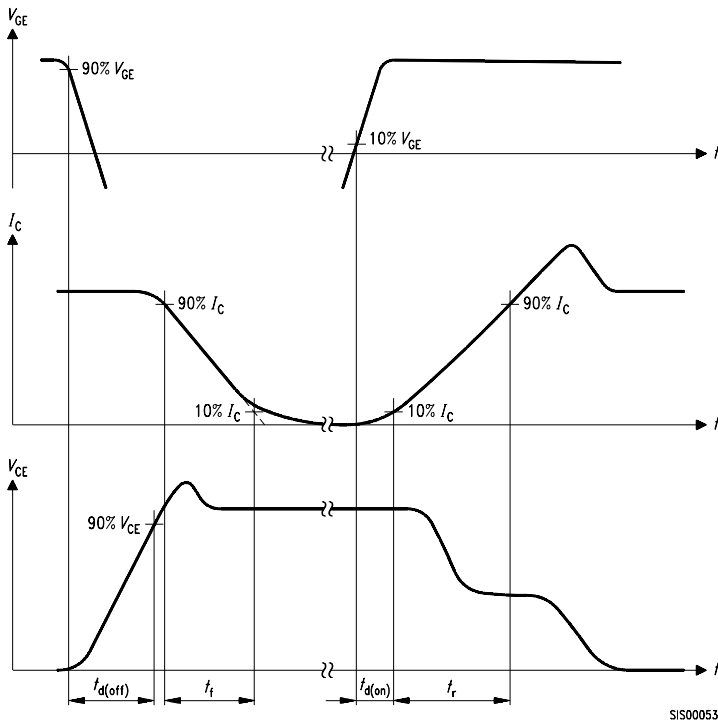| DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4.83	5.21	0.190	0.205
A1	2.27	2.54	0.089	0.100
A2	1.85	2.16	0.073	0.085
b	1.07	1.33	0.042	0.052
b1	1.90	2.41	0.075	0.095
b2	1.90	2.16	0.075	0.085
b3	2.87	3.38	0.113	0.133
b4	2.87	3.13	0.113	0.123
c	0.55	0.68	0.022	0.027
D	20.80	21.10	0.819	0.831
D1	16.25	17.65	0.640	0.695
D2	0.95	1.35	0.037	0.053
E	15.70	16.13	0.618	0.635
E1	13.10	14.15	0.516	0.557
E2	3.68	5.10	0.145	0.201
E3	1.00	2.60	0.039	0.102
e	5.44		0.214	
N	3		3	
L	19.80	20.32	0.780	0.800
L1	4.10	4.47	0.161	0.176
øP	3.50	3.70	0.138	0.146
Q	5.49	6.00	0.216	0.236
S	6.04	6.30	0.238	0.248

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SCALE

7.5mm

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04

V_{GE}

90% V_{GE}

10% V_{GE}

t

I_C

90% I_C

90% I_C

10% I_C

10% I_C

t

V_{CE}

90% V_{CE}

t

$t_{d(off)}$ t_f $t_{d(on)}$ t_r

SIS00053

Figure A. Definition of switching times

T_j (t)

$\frac{\tau_1}{r_1}$ $\frac{\tau_2}{r_2}$ $\frac{\tau_n}{r_n}$

r_1 r_2 r_n

p(t)

T_C

Figure D. Thermal equivalent circuit

V_{GE}

90% V_{GE}

10% V_{GE}

I_C

1% I_C

V_{CE}

$E_{OFF} = \int_{t_1}^{t_2} V_{CE} \times I_C \times dt$

$E_{ON} = \int_{t_3}^{t_4} V_{CE} \times I_C \times dt$

3% V_{CE}

t_1 t_2 t_3 t_4

SIS

Figure B. Definition of switching losses

½·L_σ

D.U.T. (Diode)

L

C_σ

U

R_G

D.U.T. (IGBT)

½·L_σ
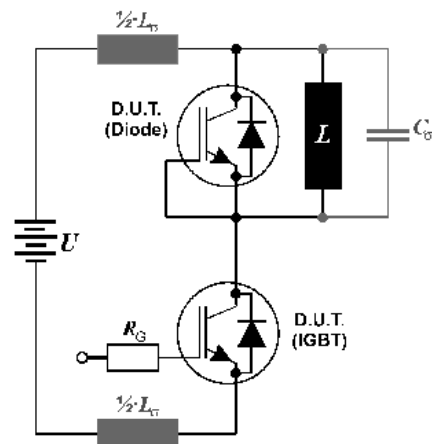
Figure E. Dynamic test circuit
Leakage inductance L_σ =180nH
and Stray capacity C_σ =55pF.

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